

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

28.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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C-RS Panasonic R-F770-ED 18-50-00	50200950	<div>18</div> <div>50</div>	VS	<div>1</div>	
A-RAS-FR4-PP-106-H72-TG170-LowFlow-EM...	50203100	<div>50</div>		<div>2</div>	A01
B-RaS-FR4-DS-1.194mm-018+018-TG150-HF...	50203144	<div>18</div> <div>1158</div> <div>18</div>	L2	<div>3</div>	A02
			L3		B00
C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...)	50202996	<div>91</div>		<div>4</div>	
C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...)	50202996	<div>0</div>		<div>5</div>	
A-RS Kupferfolie-018my 330x490mm	50200238	<div>18</div>	RS	<div>6</div>	

Thickness after Pressing

B00:

1440 µm

 Tol+:

155 µm

 Tol-:

155 µm

 Dmax:

1595 µm

 Dmin:

1285 µm

Thickness over all

0 µm

 Tol+:

0 µm

 Tol-:

0 µm

 Dmax:

0 µm

 Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

 Tol+:

155 µm

 Tol-:

155 µm

 Dmax:

1705 µm

 Dmin:

1395 µm

Measuring point:

(05) over SM and galv. Cu; both sides

nominal:

1421 µm

Version 1.2.20.35

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